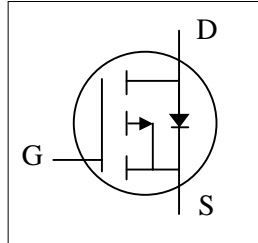




- ▼ Lower Gate Charge
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic

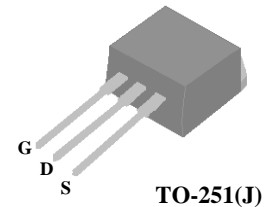
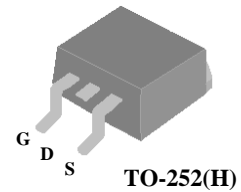


| | |
|--------------|--------------|
| BV_{DSS} | -40V |
| $R_{DS(ON)}$ | 52m Ω |
| I_D | -17A |

Description

The Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-252 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters. The through-hole version (AP9565BGJ) is available for low-profile applications.



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|---------------------------|--|------------|---------------|
| V_{DS} | Drain-Source Voltage | -40 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D @ T_C = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | -17 | A |
| $I_D @ T_C = 100^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | -11 | A |
| I_{DM} | Pulsed Drain Current ¹ | -60 | A |
| $P_D @ T_C = 25^\circ C$ | Total Power Dissipation | 25 | W |
| | Linear Derating Factor | 0.2 | W/ $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Data

| Symbol | Parameter | Value | Units |
|--------|-------------------------------------|----------|--------------|
| Rthj-c | Thermal Resistance Junction-case | Max. 5.0 | $^\circ C/W$ |
| Rthj-a | Thermal Resistance Junction-ambient | Max. 110 | $^\circ C/W$ |



AP9565BGH/J

Electrical Characteristics @ $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|--------------|--|--------------------------------|------|------|-----------|-----------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -40 | - | - | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=-10V, I_D=-8A$ | - | - | 52 | $m\Omega$ |
| | | $V_{GS}=-4.5V, I_D=-6A$ | - | - | 90 | $m\Omega$ |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -1 | - | -3 | V |
| g_{fs} | Forward Transconductance | $V_{DS}=-10V, I_D=-8A$ | - | 7.7 | - | S |
| I_{DSS} | Drain-Source Leakage Current ($T_j=25^{\circ}\text{C}$) | $V_{DS}=-40V, V_{GS}=0V$ | - | - | -10 | μA |
| | Drain-Source Leakage Current ($T_j=150^{\circ}\text{C}$) | $V_{DS}=-32V, V_{GS}=0V$ | - | - | -25 | μA |
| I_{GSS} | Gate-Source Leakage | $V_{GS}=\pm 20V$ | - | - | ± 100 | nA |
| Q_g | Total Gate Charge ² | $I_D=-8A$ | - | 7.8 | 12.5 | nC |
| Q_{gs} | Gate-Source Charge | $V_{DS}=-32V$ | - | 1.7 | - | nC |
| Q_{gd} | Gate-Drain ("Miller") Charge | $V_{GS}=-4.5V$ | - | 4.8 | - | nC |
| $t_{d(on)}$ | Turn-on Delay Time ² | $V_{DS}=-20V$ | - | 8 | - | ns |
| t_r | Rise Time | $I_D=-8A$ | - | 17 | - | ns |
| $t_{d(off)}$ | Turn-off Delay Time | $R_G=3.3\Omega, V_{GS}=-10V$ | - | 22 | - | ns |
| t_f | Fall Time | $R_D=1.25\Omega$ | - | 23 | - | ns |
| C_{iss} | Input Capacitance | $V_{GS}=0V$ | - | 530 | 850 | pF |
| C_{oss} | Output Capacitance | $V_{DS}=-25V$ | - | 110 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | $f=1.0\text{MHz}$ | - | 75 | - | pF |

Source-Drain Diode

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|----------|------------------------------------|-----------------------|------|------|------|-------|
| V_{SD} | Forward On Voltage ² | $I_S=-8A, V_{GS}=0V$ | - | - | -1.2 | V |
| t_{rr} | Reverse Recovery Time ² | $I_S=-8A, V_{GS}=0V,$ | - | 21 | - | ns |
| Q_{rr} | Reverse Recovery Charge | $dI/dt=-100A/\mu s$ | - | 14 | - | nC |

Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse test

THIS PRODUCT IS AN ELECTROSTATIC SENSITIVE, PLEASE HANDLE WITH CAUTION.

THIS PRODUCT HAS BEEN QUALIFIED FOR CONSUMER MARKET. APPLICATIONS OR USES AS CRITERIAL COMPONENT IN LIFE SUPPORT DEVICE OR SYSTEM ARE NOT AUTHORIZED.

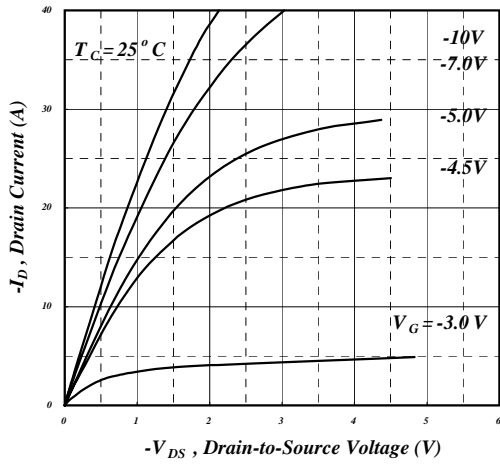


Fig 1. Typical Output Characteristics

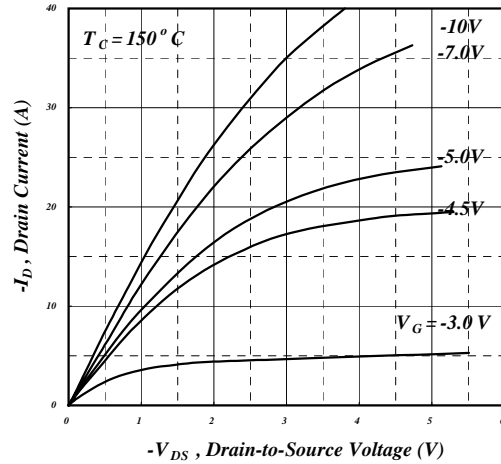


Fig 2. Typical Output Characteristics

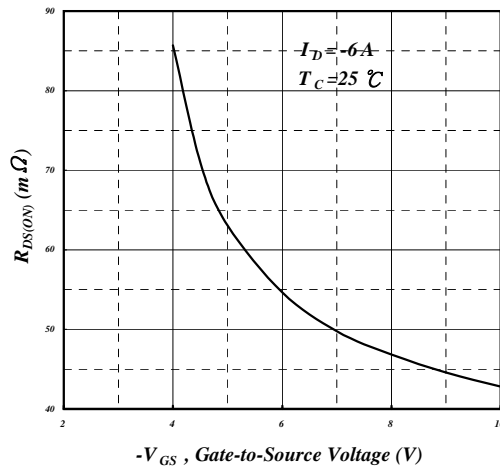


Fig 3. On-Resistance v.s. Gate Voltage

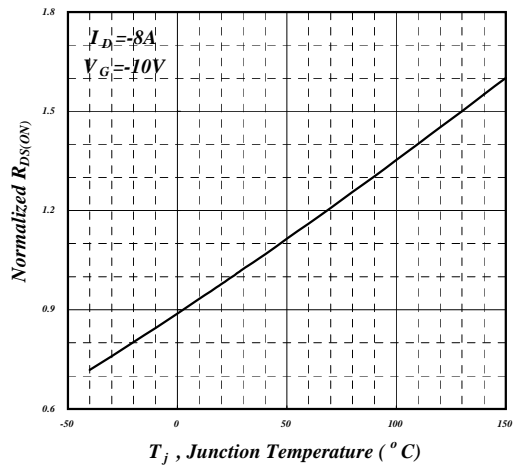


Fig 4. Normalized On-Resistance v.s. Junction Temperature

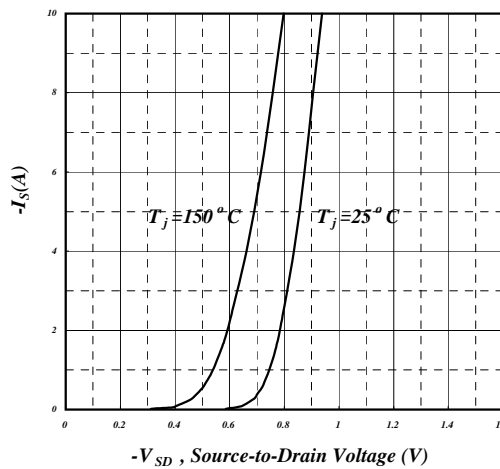


Fig 5. Forward Characteristic of Reverse Diode

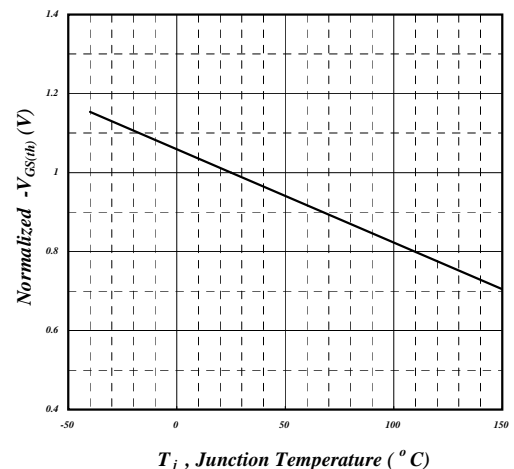


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

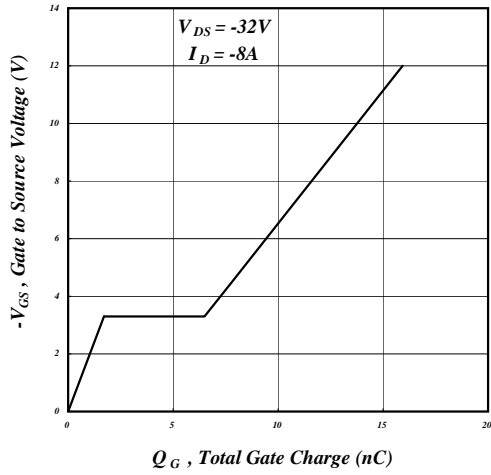


Fig 7. Gate Charge Characteristics

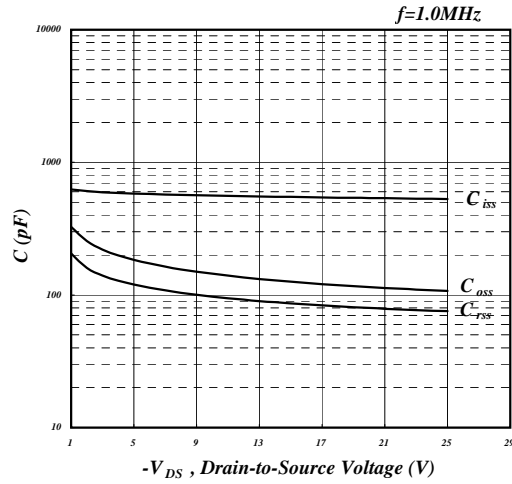


Fig 8. Typical Capacitance Characteristics

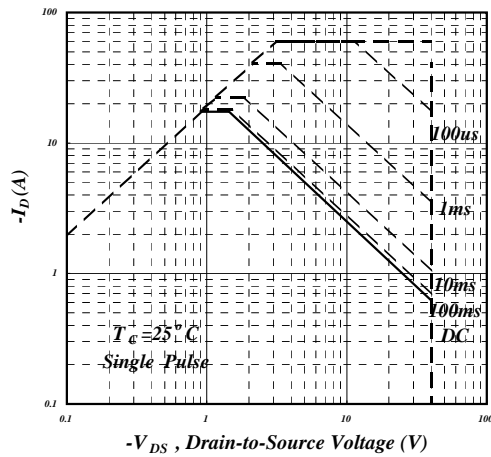


Fig 9. Maximum Safe Operating Area

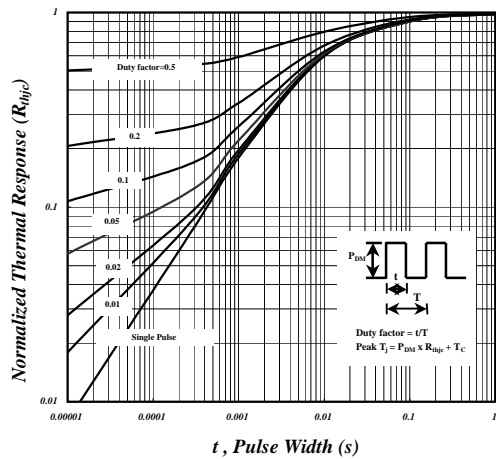


Fig 10. Effective Transient Thermal Impedance

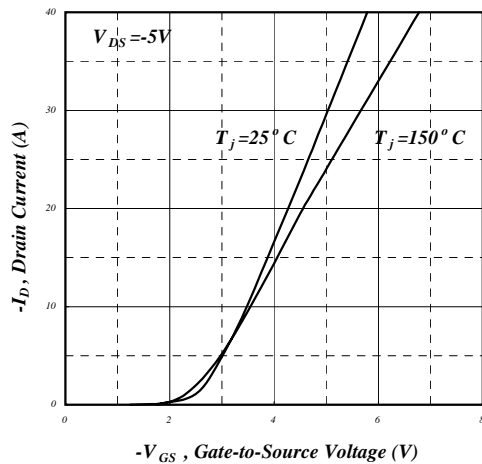


Fig 11. Transfer Characteristics

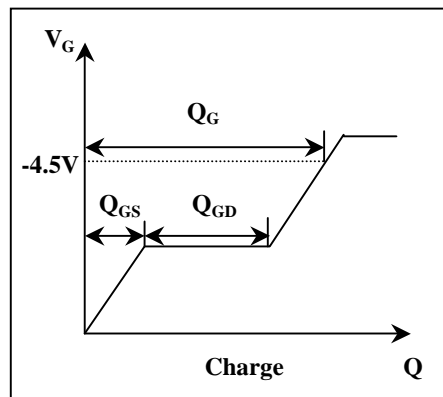
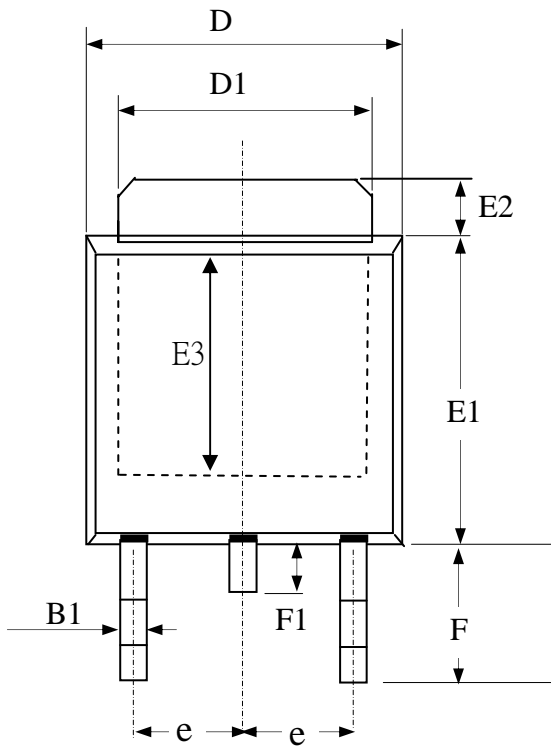


Fig 12. Gate Charge Waveform

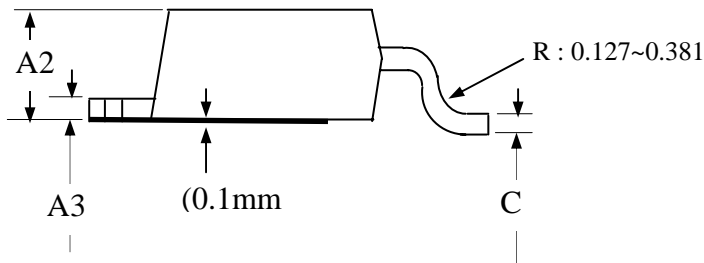


Package Outline : TO-252

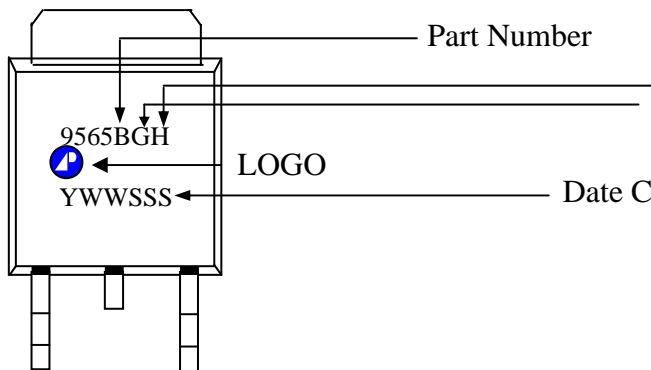


| SYMBOLS | Millimeters | | |
|---------|-------------|------|------|
| | MIN | NOM | MAX |
| A2 | 1.80 | 2.30 | 2.80 |
| A3 | 0.40 | 0.50 | 0.60 |
| B1 | 0.40 | 0.70 | 1.00 |
| D | 6.00 | 6.50 | 7.00 |
| D1 | 4.80 | 5.35 | 5.90 |
| E3 | 3.50 | 4.00 | 4.50 |
| F | 2.20 | 2.63 | 3.05 |
| F1 | 0.5 | 0.85 | 1.20 |
| E1 | 5.10 | 5.70 | 6.30 |
| E2 | 0.50 | 1.10 | 1.80 |
| e | -- | 2.30 | -- |
| C | 0.35 | 0.50 | 0.65 |

- 1.All Dimensions Are in Millimeters.
- 2.Dimension Does Not Include Mold Protrusions.



Part Marking Information & Packing : TO-252



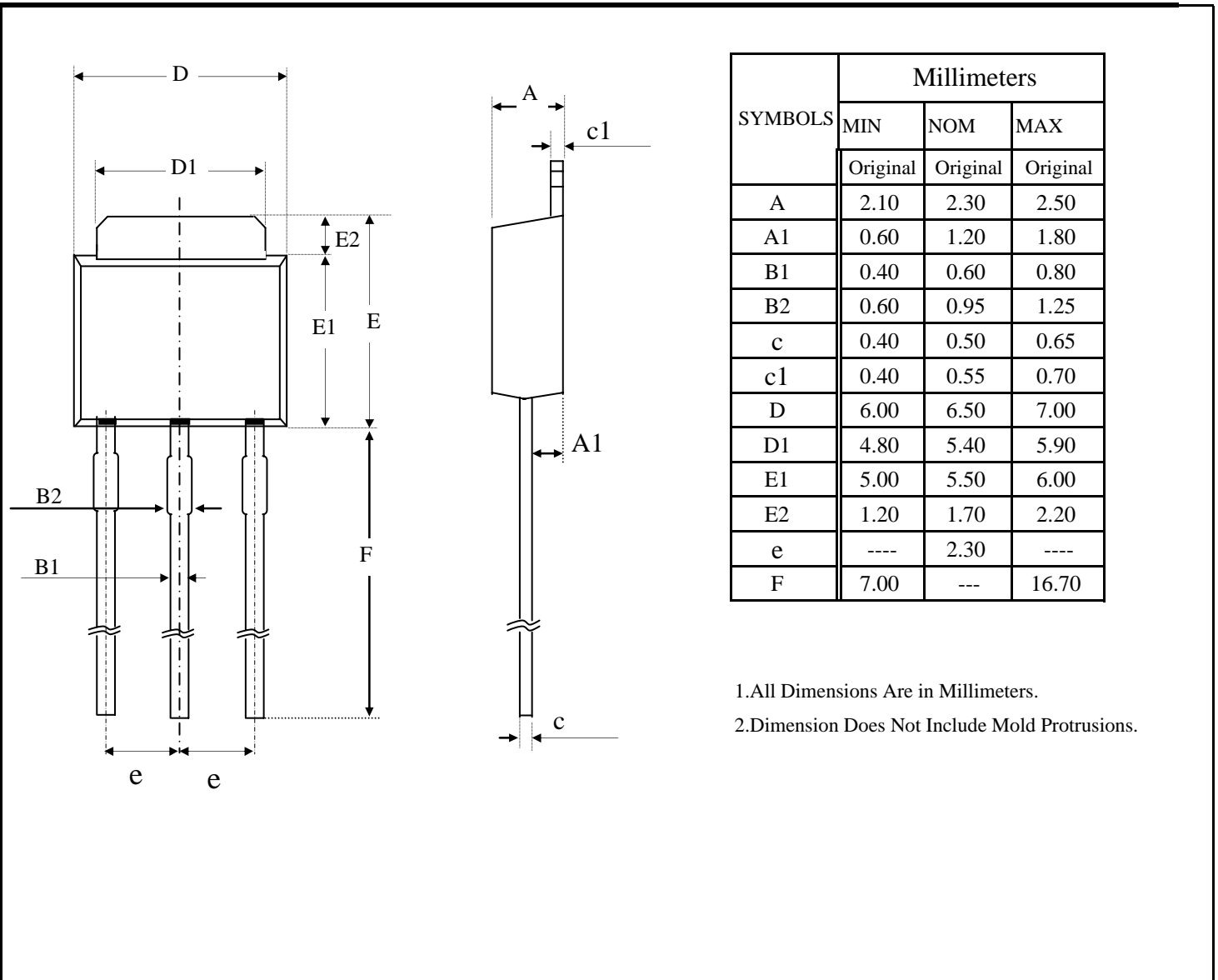
Package Code
meet Rohs requirement

Date Code (YWWSSS)

Y : Last Digit Of The Year

WW : Week

SSS : Sequence



Part Marking Information & Packing : TO-251 (low voltage)

